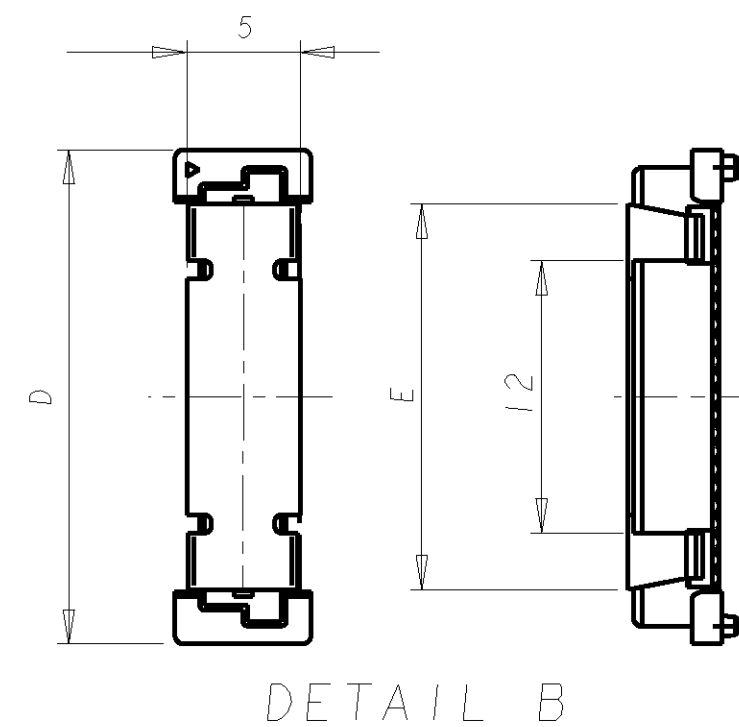
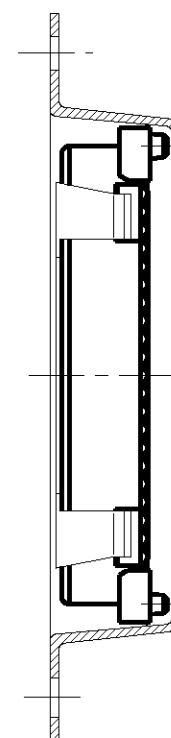
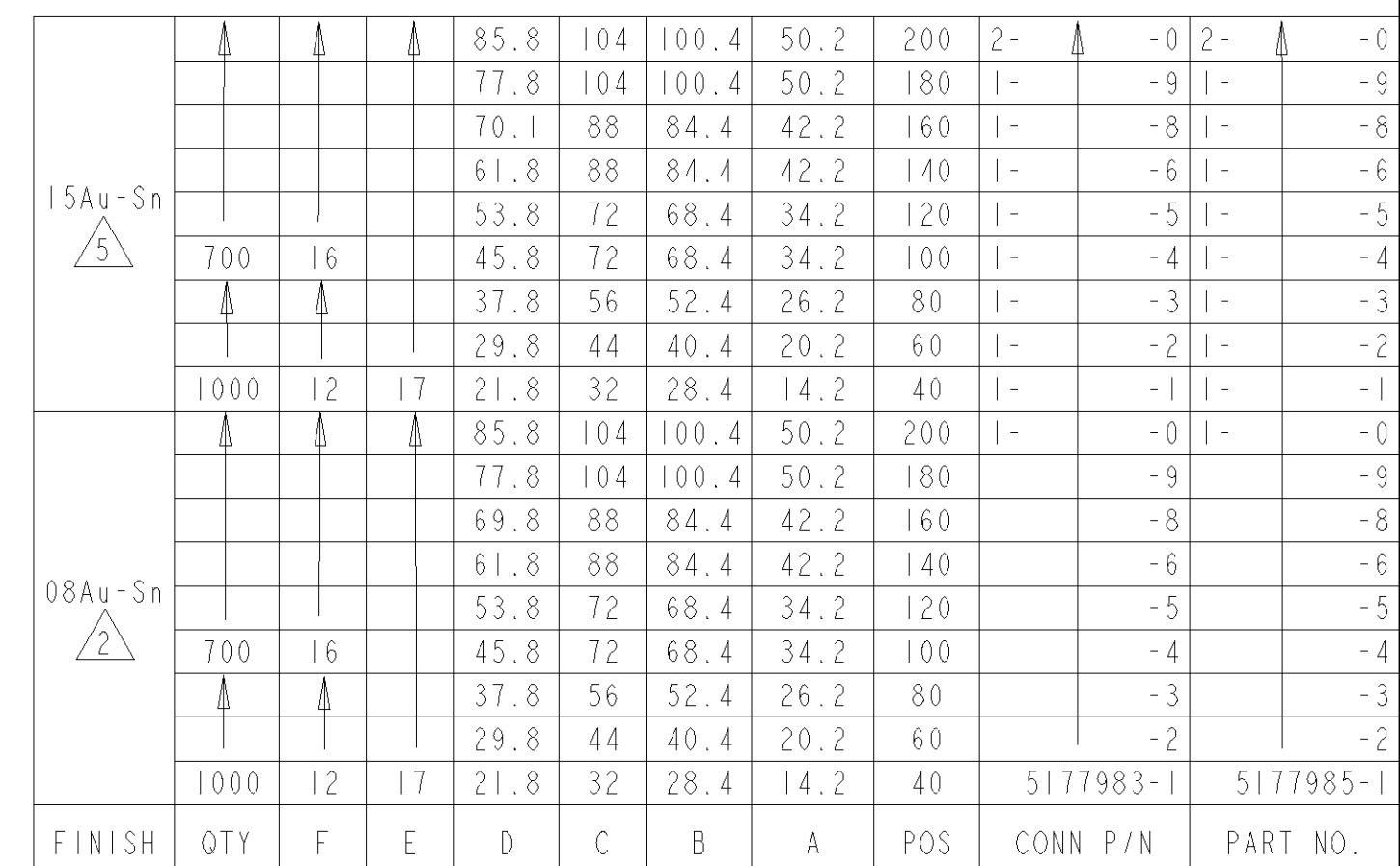
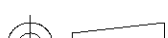




- NOTES:
- 1 MATERIAL: HOUSING: L.C.P (HIGH TEMP THERMOPLASTIC)
UL 94V-0,NATURAL.
CONTACT: BERYLIUM COPPER.
- 2 FINISH: CONTACT AREA: 0.0002 MIN GOLD ON
0.0013 MIN ALL OVER NICKEL.
SOLDERING AREA: 0.002 MIN MATTE TIN.
3. POSITION SERIES: SEE TABLE.
4. CONN STACK HEIGHT COMBINE OF PLUG "Y"H VS REC "X"H.
STACK HEIGHT = Y + X - 5
- 5 FINISH: CONTACT AREA: 0.00038 MIN GOLD ON
0.0013 MIN ALL OVER NICKEL.
SOLDERING AREA: 0.002 MIN MATTE TIN.



DIMENSIONS: mm 		DWN SK LEAW 17MAY2004 CHK ERIC TNG 17MAY2004		 TE Connectivity	
		APVD SE I FONG PRODUCT SPEC 108-5390 APPLICATION SPEC 114-5254			
MATERIAL 		TOLERANCES UNLESS OTHERWISE SPECIFIED: 0 PLC ±.3 1 PLC ±0.25 2 PLC ±0.2 3 PLC ±.2 4 PLC ±.3° ANGLES FINISH		NAME RECEPTACLE ASSEMBLY 5H TYPE (.05 BOSS LENGTH) FOR FH 0.8 B-T-B CONN, ON TAPING SIZE A2 CASE CODE 00779 DRAWING NO C=5177985	
SEE P/N TABLE		WEIGHT - CUSTOMER DRAWING		SCALE 3:1 SHEET 1 OF 1 REV P	